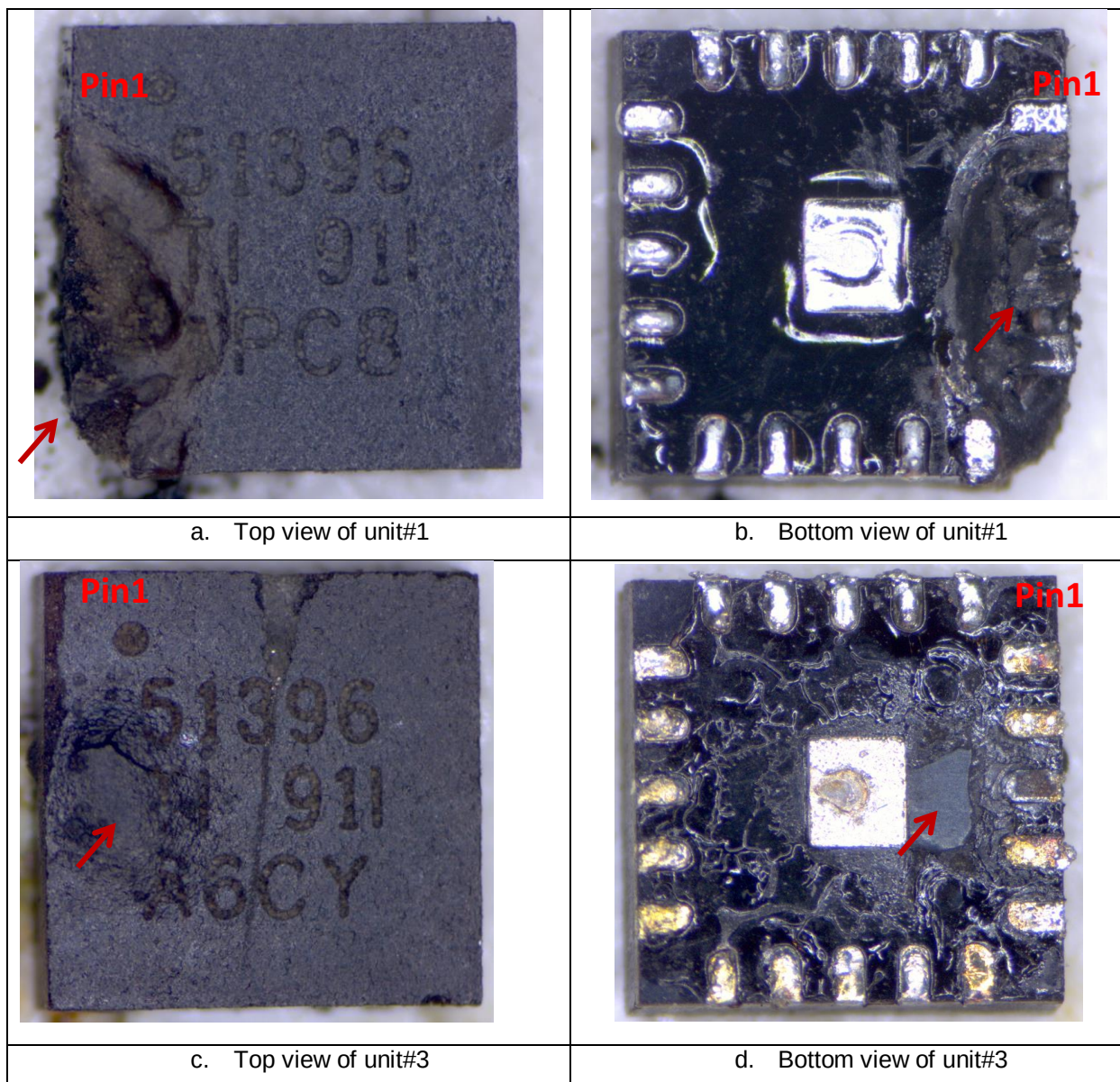


- **CRU Description:**

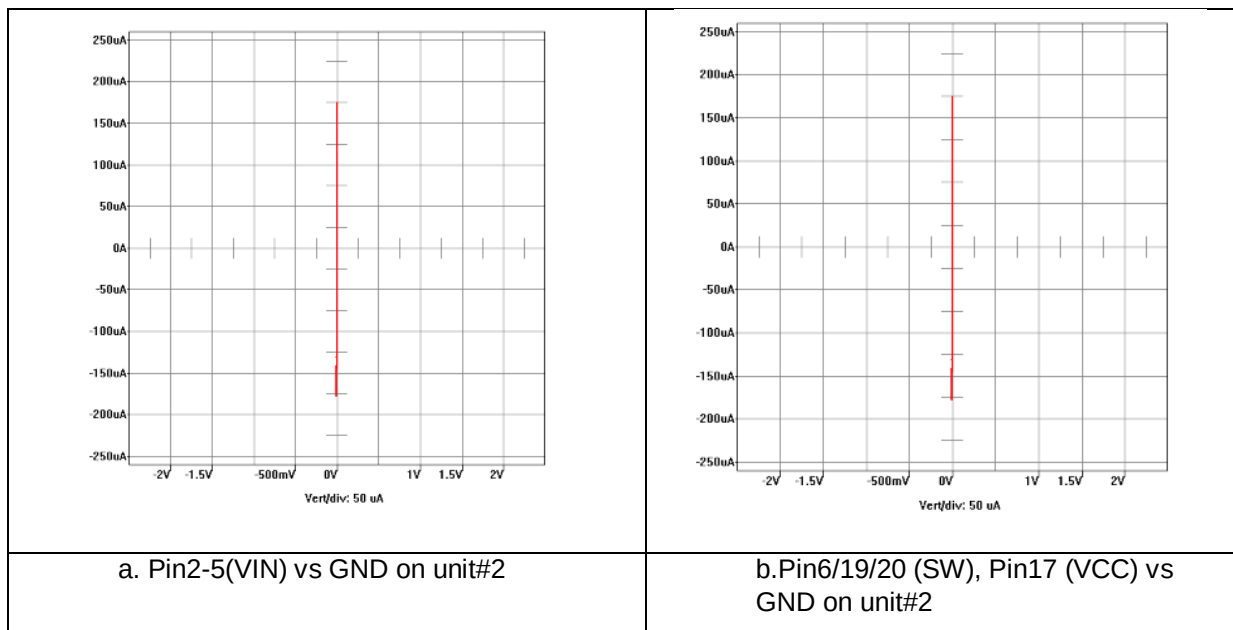
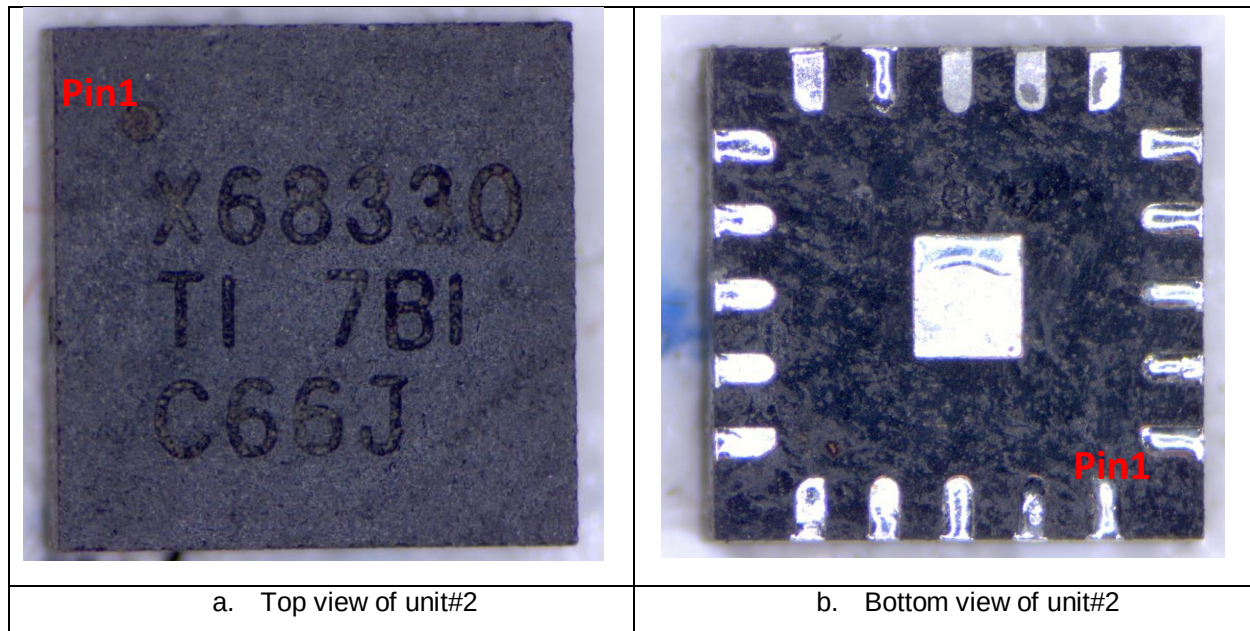
#1: field return, VIN/SW/VCC short, package damaged, request decap to review all damage area
 #2: simulation test with high VIN, old marking as TPS568330, 7BC66JI, need IV test and decap result
 #3 & #4: simulation test with resistor start, #4 with longer power up time and damaged package, need IV test and decap result to see if similar EIPD as #1

- **FA Result:**

Unit#1 & 3 is damaged too bad to decap, both units are damaged at VIN (pin2-5).



Unit#2 was submitted to do Curve Trace Test. Short failure was observed at Pin2-5(VIN), Pin6/19/20 (SW), Pin17 (VCC) vs GND on the returned unit#2.



- Decapsulation:**

Returned unit#2 was de-capped with mixed acid to expose die surface.

- **Internal Optical Inspection:**

Returned unit#2 was inspected with optical microscope.
EIPD was observed at the pin2-5 of the returned unit#2.

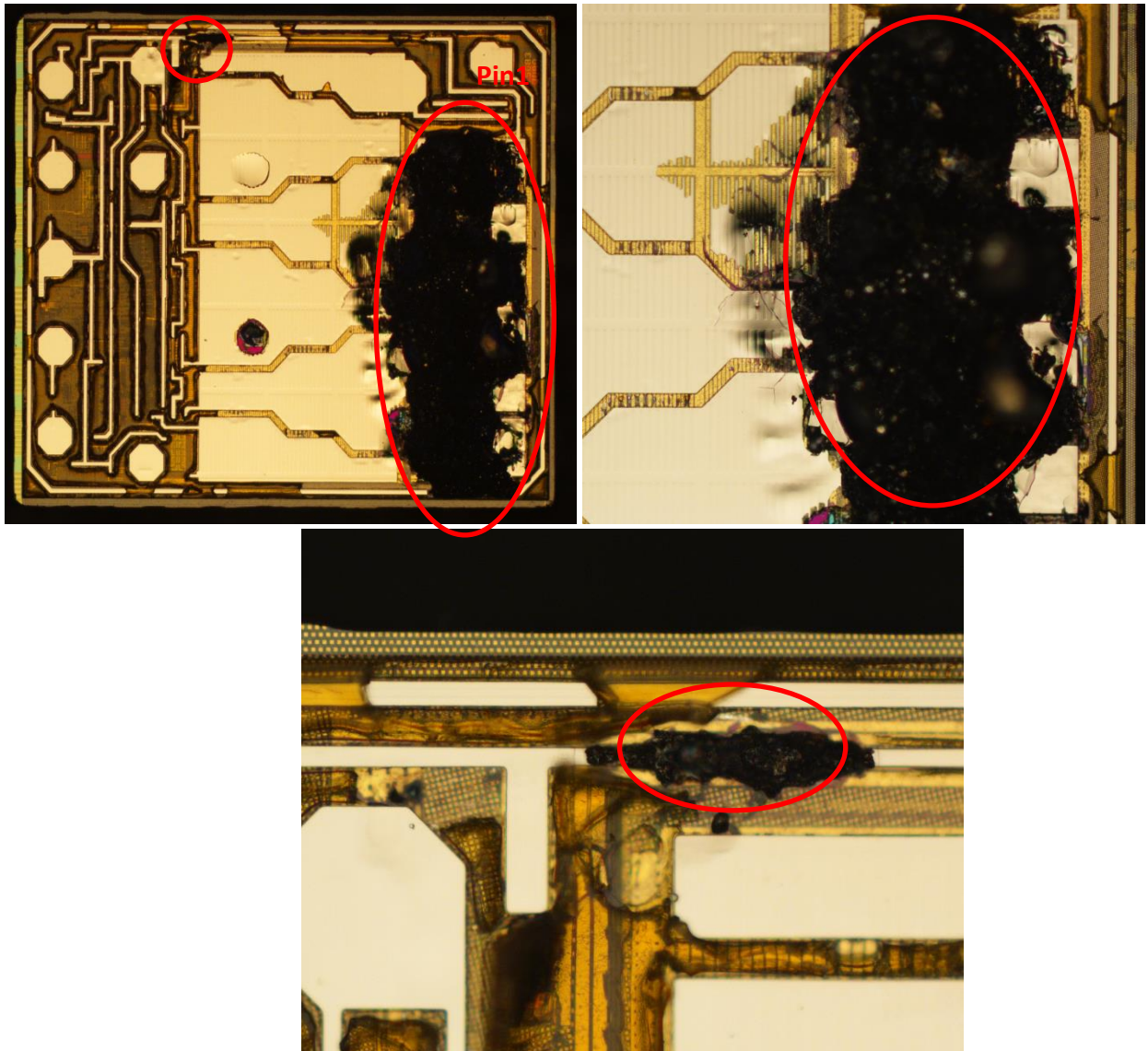
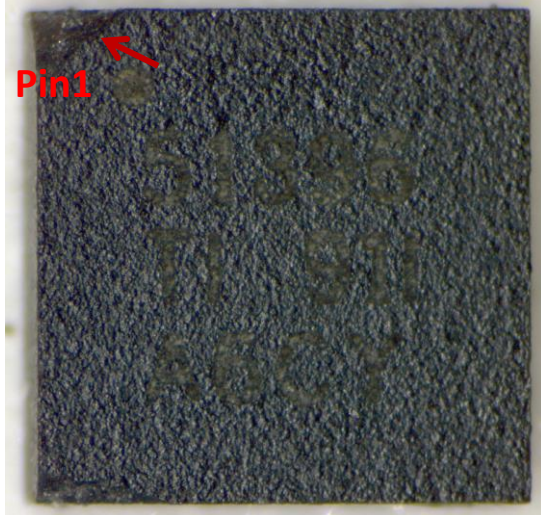
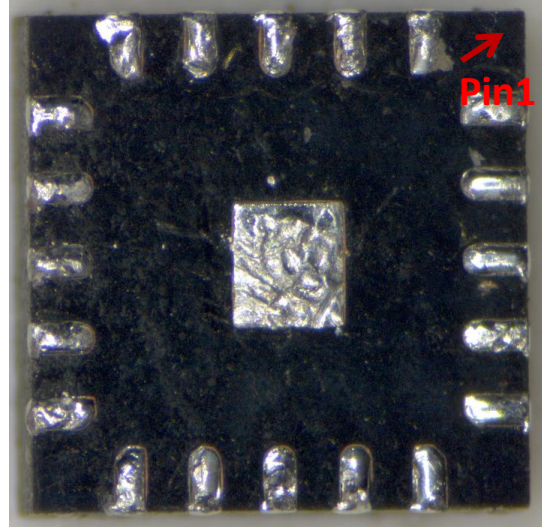


Fig. 4: Optical images of returned unit. EIPD was observed on the unit#2.

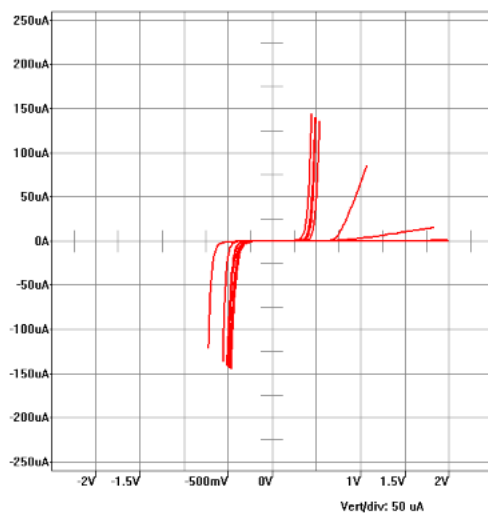
Unit#4: No open and short was observed.



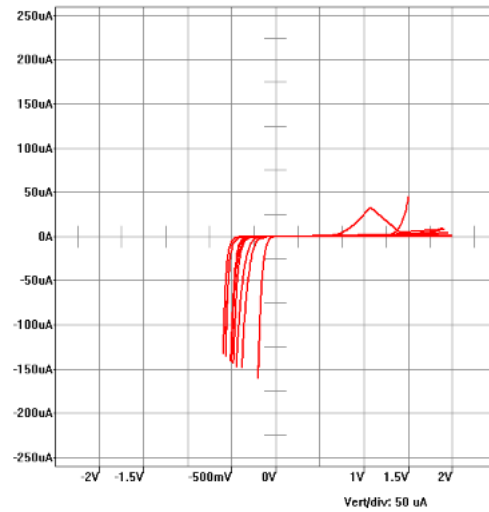
a. Top view of unit#4



b. Bottom view of unit#4



c. Pin vs all pins on unit#4



d. Pin vs GND on unit#4